

L Number	Hits	Search Text	DB	Time stamp
-	164	(710/317).CCLS.	USPAT; US-PGPUB	2004/01/09 12:03
-	18	((710/317).CCLS.) and analog and digital	USPAT; US-PGPUB	2003/12/19 14:17
-	37232	microcontroller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:51
-	14360	microcontroller and analog and digital	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:51
-	2326	(microcontroller and analog and digital) and (wirebond or "wire bond" or pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:52
-	1714	((microcontroller and analog and digital) and (wirebond or "wire bond" or pad)) and processor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:52
-	1459	((microcontroller and analog and digital) and (wirebond or "wire bond" or pad)) and processor) and (crossbar or switch\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 13:55
-	1458	((microcontroller and analog and digital) and (wirebond or "wire bond" or pad)) and processor) and (crossbar or switch\$5)	USPAT; US-PGPUB	2003/12/19 13:56
-	37232	microcontroller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:11
-	316838	analog same digital	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:11
-	13231	microcontroller and (analog same digital)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:12
-	0	((710/317).CCLS.) and wirebond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:12
-	8	(microcontroller and (analog same digital)) and wirebond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:12
-	62	(microcontroller and (analog same digital)) and (wirebond or "wire bond")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:13
-	55	((microcontroller and (analog same digital)) and (wirebond or "wire bond")) and (processor or microprocessor or cpu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/19 14:14

-	48	((microcontroller and (analog same digital)) and (wirebond or "wire bond")) and (processor or microprocessor or cpu) and (switch\$4 or crossbar or "cross bar")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:16
-	0	((microcontroller and (analog same digital)) and (wirebond or "wire bond")) and (processor or microprocessor or cpu) and (switch\$4 or crossbar or "cross bar")) not microcontroller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:16
-	316838	analog same digital	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:17
-	803	(analog same digital) and (wirebond or "wire bond")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:17
-	493	((analog same digital) and (wirebond or "wire bond")) and (switch\$4 or crossbar or "cross bar")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 14:18
-	301	((analog same digital) and (wirebond or "wire bond")) and (switch\$4 or crossbar or "cross bar")) and (processor or microprocessor or cpu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/19 17:05
-	2	("6144327") or ("5202687").PN.	USPAT; US-PGPUB	2003/12/19 17:06
-	1	("6192431").PN.	USPAT; US-PGPUB	2003/12/22 13:19
-	0	6192431.URPN.	USPAT	2003/12/22 13:15
-	0	6192431.URPN.	USPAT	2003/12/22 13:15
-	6	("5701517" "5715197" "5737764" "5748982" "5822610" "5835965").PN.	USPAT	2003/12/22 13:15
-	1649	(257/666).CCLS.	USPAT; US-PGPUB	2003/12/22 13:19
-	1335	((257/666).CCLS.) and (wirebond or "wire bond" or pad)	USPAT; US-PGPUB	2003/12/22 14:01
-	87	((257/666).CCLS.) and (wirebond or "wire bond" or pad) and (processor or cpu)	USPAT; US-PGPUB	2003/12/22 13:21
-	81	((257/666).CCLS.) and (wirebond or "wire bond" or pad) and (processor or cpu) and (switch or select\$6 or configura\$5)	USPAT; US-PGPUB	2003/12/22 13:23
-	64	((257/666).CCLS.) and (wirebond or "wire bond" or pad) and (processor or cpu) and (switch or select\$6 or configurable or reconfigurable or re-configurable)	USPAT; US-PGPUB	2003/12/22 13:23
-	429	((257/666).CCLS.) and (wirebond or "wire bond")	USPAT; US-PGPUB	2003/12/22 14:03
-	43	((257/666).CCLS.) and (wirebond or "wire bond")) and (processor or cpu)	USPAT; US-PGPUB	2003/12/22 14:02
-	482	((257/666).CCLS.) and ((wirebond or "wire bond") next10 (processor or cpu))	USPAT; US-PGPUB	2003/12/22 14:03
-	422718	("wire bond" or wirebond) next10 (processor or cpu)	USPAT; US-PGPUB	2003/12/22 14:04
-	482	("wire bond" or wirebond) next10 (processor or cpu) and ((257/666).CCLS.)	USPAT; US-PGPUB	2003/12/22 14:04
-	17	("wirebond pad" or "wire bond pad") near10 (processor or cpu)	USPAT; US-PGPUB	2003/12/22 14:07
-	48	(wirebond or "wire bond") near10 (processor or cpu)	USPAT; US-PGPUB	2003/12/22 14:08
-	8	((wirebond or "wire bond") near10 (processor or cpu)) same (switch or configura\$6 or select\$6)	USPAT; US-PGPUB	2003/12/22 14:10

-	1	("5563529").PN.	USPAT;	2003/12/22
-	1	("6445242").PN.	US-PGPUB	14:12
-	1133	(257/676).CCLS.	USPAT;	2003/12/22
-	207	"wirebond pad"	US-PGPUB	14:14
-	1183	"wire bond pad"	USPAT;	2003/12/22
-	1351	"wirebond pad" or "wire bond pad"	US-PGPUB	14:15
-	188	("wirebond pad" or "wire bond pad") and processor	USPAT;	2003/12/22
-	2443436	switch\$6 or select\$6 or reconfigurable or re-configurable or configurable	US-PGPUB	14:17
-	0	((("wirebond pad" or "wire bond pad") near10 (processor or cpu)) near10 (switch\$5 or select\$5 or configurable or reconfigurable or re-configurable))	USPAT;	2003/12/22
-	0	((("wirebond pad" or "wire bond pad") near10 (processor or cpu)) same (switch\$5 or select\$5 or configurable or reconfigurable or re-configurable))	US-PGPUB	14:18
-	1	((("wirebond pad" or "wire bond pad") near10 (processor or cpu)) and (switch\$5 or select\$5 or configurable or reconfigurable or re-configurable))	USPAT;	2003/12/22
-	11	((("wirebond pad" or "wire bond pad") near10 (processor or cpu)) and (switch\$5 or select\$5 or configurable or reconfigurable or re-configurable))	US-PGPUB	14:20
-	954	(326/38).CCLS.	USPAT;	2003/12/22
-	2	((326/38).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:00
-	1058	(326/41).CCLS.	USPAT;	2003/12/22
-	1	((326/41).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:02
-	319	(257/e23.011).CCLS.	USPAT;	2003/12/22
-	3	((257/e23.011).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:03
-	65	(257/e23.032).CCLS.	USPAT;	2003/12/22
-	0	((257/e23.032).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:04
-	534	(257/e23.079).CCLS.	USPAT;	2003/12/22
-	11	((257/e23.079).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:07
-	401	(710/316).CCLS.	USPAT;	2003/12/22
-	0	((710/316).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:11
-	164	(710/317).CCLS.	USPAT;	2003/12/22
-	0	((710/317).CCLS.) and ("wirebond pad" or "wire bond pad")	US-PGPUB	16:12
-	82	((326/38).CCLS.) and ((326/41).CCLS.) and (pad and processor or microprocessor)	USPAT;	2003/12/22
-	42	((326/38).CCLS.) and ((326/41).CCLS.) and (pad and (processor or microprocessor))	US-PGPUB	16:27
-	35	((326/38).CCLS.) and ((326/41).CCLS.) and (pad and (processor or microprocessor))) and (configurable or reconfigurable or re-configurable)	USPAT;	2003/12/22
-			US-PGPUB	16:28

-	31	((((326/38).CCLS.) and ((326/41).CCLS.) and (pad and (processor or microprocessor))) and (configurable or reconfigurable or re-configurable)) and switch\$6	USPAT; US-PGPUB	2003/12/22 16:31
-	382	(configurable or reconfigurable or re-configurable) near6 pin	USPAT; US-PGPUB	2003/12/22 16:50
-	70	((configurable or reconfigurable or re-configurable) near6 pin) and pad and (processor or microprocessor) and (switch or connect\$5 or select\$4)	USPAT; US-PGPUB	2003/12/22 16:50
-	234	(configurable or reconfigurable or re-configurable) near3 pin	USPAT; US-PGPUB	2003/12/22 16:50
-	34	((configurable or reconfigurable or re-configurable) near3 pin) and pad and (processor or microprocessor) and (switch or connect\$5 or select\$4)	USPAT; US-PGPUB	2003/12/22 17:33
-	2289	(257/666,676).CCLS.	USPAT; US-PGPUB	2003/12/22 17:36
-	0	((257/666,676).CCLS.) and ((326/38).CCLS.) and ((326/41).CCLS.) and ((257/e23.011).CCLS.) and ((257/e23.032).CCLS.) and ((257/e23.079).CCLS.) and ((710/316).CCLS.) and ((710/317).CCLS.) and microcontroller	USPAT; US-PGPUB	2003/12/22 17:37
-	142	((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller	USPAT; US-PGPUB	2003/12/22 17:38
-	71	((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller and pad	USPAT; US-PGPUB	2003/12/22 17:39
-	57	((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller and pad and (processor or microprocessor)	USPAT; US-PGPUB	2003/12/22 18:09
-	0	6509758.URPN.	USPAT	2003/12/22 17:50
-	12	("4642561" "4800294" "4963768" "5107146" "5107230" "5289116" "5473758" "5511182" "5563526" "5686844" "6057705" "6246258").PN.	USPAT	2003/12/22 17:51
-	14	((((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller and pad) not (((257/666,676).CCLS.) or ((326/38).CCLS.) or ((326/41).CCLS.) or ((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or ((710/316).CCLS.) or ((710/317).CCLS.)) and microcontroller and pad and (processor or microprocessor))	USPAT; US-PGPUB	2003/12/22 18:09
-	0	6509758.URPN.	USPAT	2003/12/24 13:48

-	12	("4642561" "4800294" "4963768" "5107146" "5107230" "5289116" "5473758" "5511182" "5563526" "5686844" "6057705" "6246258").PN.	USPAT	2003/12/24 13:48
-	12	("4642561" "4800294" "4963768" "5107230" "5289116" "5473758" "5511182" "5563526" "5686844" "5724009" "6057705" "6246258").PN.	USPAT	2003/12/24 13:49
-	23	("4472647" "4698526" "4877978" "4896060" "4902917" "4930112" "4978905" "5084635" "5144167" "5153450" "5157282" "5161124" "5162672" "5300832" "5309044" "5345112" "5353250" "5359240" "5402018" "5406139" "5600267" "5732027" "6047352").PN.	USPAT	2003/12/24 13:50
-	12	("4642561" "4800294" "4963768" "5107146" "5107230" "5289116" "5473758" "5511182" "5563526" "5686844" "6057705" "6246258").PN.	USPAT	2003/12/30 13:41
-	0	6509758.URPN.	USPAT	2003/12/30 14:17
-	12	("4642561" "4800294" "4963768" "5107230" "5289116" "5473758" "5511182" "5563526" "5686844" "5724009" "6057705" "6246258").PN.	USPAT	2003/12/30 14:17
-	3	("5757207" "5768598" "5883526").PN.	USPAT	2003/12/30 17:28
-	0	6188241.URPN.	USPAT	2003/12/30 17:29
-	6	("5701517" "5715197" "5737764" "5748982" "5822610" "5835965").PN.	USPAT	2003/12/30 17:29
-	27	"analog circuit" and "digital circuit" and switch and pad and processor and (microcontroller or "micro controller" or micro-controller)	USPAT; US-PGPUB	2003/12/30 17:52
-	0	20020108006.URPN.	USPAT	2003/12/30 17:50
-	0	"analog circuit" and "digital circuit" and switch and pad and processor and (microcontroller or "micro controller" or micro-controller)	EPO; JPO; DERWENT; IBM_TDB	2003/12/30 17:52
-	36	"analog circuit" and "digital circuit" and switch and pad and (processor or microprocessor or cpu) and (microcontroller or "micro controller" or micro-controller)	USPAT; US-PGPUB	2003/12/30 17:53
-	0	6192431.pn. and (analog or digital)	USPAT; US-PGPUB	2004/01/09 12:04
-	1	6192431.pn.	USPAT; US-PGPUB	2004/01/09 13:09
-	883353	(gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:14
-	19576	((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:15
-	3286	((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:15

-	2929	(((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:16
-	2581	(((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)) and switch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:16
-	0	((((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)) and switch\$4) and ("selectively connects" near10 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:17
-	1325	((((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)) and switch\$4) and selectively	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:18
-	27	((((gate or counter or latch\$3 or decoder or encoder or register or flip-flop or "flip flop" or timer) and (filter or amplifier or switch or clipper or limiter or summer or buffer)) and microcontroller) and pad) and (processor or microprocessor)) and switch\$4) and "selectively connects"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/09 13:18



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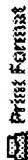
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Wirebond

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1 **Transient three dimensional simulation of mold filling and wire sweep in an overmold BGA package**

Tay, A.A.O.; Lee, W.H.;

Electronic Components and Technology Conference, 2002. Proceedings. 52nd , 28-31 May 2002

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[Abstract] [PDF Full-Text (787 KB)] **IEEE CNF**

2 **Wirebonding: reinventing the process for MCMs**

Charles, H.K. Jr.; Mach, K.J.; Edwards, R.L.; Lehtonen, S.J.; Lee, D.M.; Multichip Modules and High Density Packaging, 1998. Proceedings. 1998 7th International Conference on , 15-17 April 1998

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[Abstract] [PDF Full-Text (212 KB)] **IEEE CNF**

3 **A new approach to the robust wirebonding**

Cuong Van Pham; Huth, K.;
Advanced Packaging Materials: Processes, Properties and Interfaces, 2001.
Proceedings. International Symposium on , 11-14 March 2001
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[Abstract] [PDF Full-Text (852 KB)] **IEEE CNF**

4 **The effect of wirebond geometry and die setting on wire sweep**

Tay, A.A.O.; Yeo, K.S.; Wu, J.H.;
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IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology,
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[Abstract] [PDF Full-Text (668 KB)] **IEEE JNL**

5 **Analysis and application of vibration behaviour for wirebonding capillary by transmission laser vibrometer**

Tamura, Y.; Miyahara, Y.; Suzuki, H.;
Electronics Manufacturing Technology Symposium, 1998. Twenty-Third IEEE/CPMT ,
19-21 Oct. 1998
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[Abstract] [PDF Full-Text (450 KB)] **IEEE CNF**

6 **High-frequency wirebonding: process and reliability implications**

Charles, H.K., Jr.; Mach, K.J.; Lehtonen, S.J.; Francomacaro, A.S.; DeBoy, J.S.;
Edwards, R.L.;
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May 2002
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[Abstract] [PDF Full-Text (1140 KB)] **IEEE CNF**

7 **Wirebond reliability in IGBT-power modules: application of high resolution strain and temperature mapping**

Mehrotra, V.; Jun He; Dadkhah, M.S.; Rugg, K.; Shaw, M.C.;
Power Semiconductor Devices and ICs, 1999. ISPSD '99. Proceedings., The 11th International Symposium on , 26-28 May 1999
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[Abstract] [PDF Full-Text (380 KB)] **IEEE CNF**

8 **Wirebonding Reliability Techniques and Analysis**

Ebel, G.; Jeffery, J.; Farrell, J.;
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[Abstract] [PDF Full-Text (1024 KB)] **IEEE JNL**

9 **DC to 100 GHz chip-to-chip interconnects with reduced tolerance sensitivity by adaptive wirebonding**

Goebel, U.;
Electrical Performance of Electronic packaging, 1994., IEEE 3rd Topical Meeting on , 2-4 Nov. 1994
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[Abstract] [PDF Full-Text (276 KB)] **IEEE CNF**

- 10 **The effect of fillet height and bondline thickness on the mechanical performance of a plastic package**
Rasihah, I.J.; Breach, C.;
Electronic Materials and Packaging, 2000. (EMAP 2000). International Symposium on ,
30 Nov.-2 Dec. 2000
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[Abstract] [PDF Full-Text (368 KB)] **IEEE CNF**

- 11 **Analysis of wirebonding techniques for contacting high concentrator solar cells**
Rey-Stolle, I.; Algora, C.;
Advanced Packaging, IEEE Transactions on [see also Components, Packaging and
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Volume: 26 Issue: 1 , Feb. 2003
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[Abstract] [PDF Full-Text (357 KB)] **IEEE JNL**

- 12 **A three-dimensional modeling of wire sweep incorporating resin cure**
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IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology,
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[Abstract] [PDF Full-Text (208 KB)] **IEEE JNL**

- 13 **Integrated Taguchi method and neural network analysis of physical**

profiling in the wirebonding process

Yu-Lung Lo; Tsao, C.C.;
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15 70 µm fine pitch wirebonding

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[Abstract] [PDF Full-Text (1271 KB)] **IEEE CNF**

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